

### N & P Channel 60-V Dual MOSFETs

### Description

These N+P dual Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### Features

- Fast switching
- Green Device Available
- Suit for 4.5V Gate Drive Applications
- RoHS compliant package

#### **Applications**

- DC Fan
- Motor Drive Applications
- Networking
- Half / Full Bridge Topology

Package type: SO-8

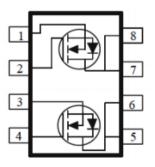
### **Packing & Order Information**

3,000/Reel

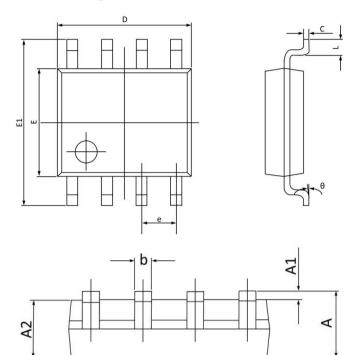


RoHS COMPLIANT

Graphic symbol



### SO-8 Package information



Symbol	Dimensions I	n Millimeters	Dimension	s In Inches
Symbol	MAX	MIN	MAX	MIN
A	1.750	1.350	0.069	0.053
A1	0.250	0.100	0.010	0.004
A2	1.500	1.300	0.059	0.051
b	0.490	0.350	0.019	0.014
C	0.260	0.190	0.010	0.007
D	5.100	4.700	0.201	0.185
E	4.100	3.700	0.161	0.146
E1	6.200	5.800	0.244	0.228
e	1.27BSC 0.05BSC		BSC	
L	0.900	0.400	0.035	0.016
θ	8°	0°	8°	0°



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### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

WE WINDOW RATE TOO FIND ELLIC TRICAL CHARACTERISTICS										
Absolute N	Absolute Maximum Ratings (T <sub>A</sub> =25°C unless otherwise specified)									
Symbol	Parameter	Nch Limit	Pch Limit	Unit						
$V_{DS}$	Drain-Source Voltage	60	-60	V						
$V_{GS}$	Gate-Source Voltage	±20	±20	V						
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> =25°C)	4.5	-3.5	A						
ID	Drain Current - Continuous (T <sub>C</sub> =70°C)	2.85	-2.21	A						
$I_{DM}$	Drain Current - Pulsed <sup>1</sup>	18	-14	A						
D	Power Dissipation (T <sub>C</sub> =25°C)	3.	W							
$P_{\mathrm{D}}$	Power Dissipation - Derate above 25°C	0.0	)28	W/°C						
T <sub>J</sub>	Storage Temperature Range	-55 to	-55 to 150							
T <sub>STG</sub>	Operating Junction Temperature Range	-55 to 150 °C		°C						

Thermal Resistance Ratings								
Symbol	Parameter	Typ.	Max.	Units				
$R_{\theta JA}$	Thermal Resistance Junction to ambient		75	°C/W				
$R_{\theta JC}$	Thermal Resistance Junction to Case		35	C/W				

## N-CH Electrical Characteristics (TJ=25 °C, unless otherwise)

Off Charac	teristics					
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = V_{GS}, I_D = 250uA$	60			V
$\Delta BV_{DSS}$ / $\Delta TJ$	BV <sub>DSS</sub> Temperature Coefficient	Reference to $25^{\circ}$ C , $I_D = 1 \text{ mA}$		0.05		V/°C
IGSS	Gate-Source Leakage Current	$V_{DS}=0~V~,~V_{GS}=~\pm20~V$			±100	nA
Idss	Drain-Source Leakage Current	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, TJ = 25 ^{\circ}\text{C}$ $V_{DS} = 48 \text{ V}, V_{GS} = 0 \text{ V}, TJ = 125 ^{\circ}\text{C}$			1 10	uA

On Characteristics								
Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units		
$R_{DS(on)} \\$	Static Drain-Source	$V_{GS} = 10 \text{ V}, I_{D} = 6 \text{ A}$		45	54	mΩ		
	On-Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 3 \text{ A}$		52	63	11122		
$V_{GS(th)}$	Gate Threshold Voltage	V V 1 250 A	1.2	1.8	2.5	V		
$\Delta V_{GS(th)}$	Temperature Coefficient	$V_{GS} = V_{DS}$ , $I_D = 250 uA$		-4.2		mV/°C		
g fs	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_{D} = 4 \text{ A}$		4.2		S		



## N & P Channel 60-V Dual MOS FETs

Dynamic a	Dynamic and switching Characteristics										
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units					
$Q_g$	Total Gate Charge <sup>2,3</sup>			14	21	nC					
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>	$V_{DS} = 30 \text{ V}, I_D = 4 \text{ A},$ $V_{GS} = 10 \text{ V}$		2.9	5	nC					
$Q_{\mathrm{gd}}$	Gate-Drain Charge <sup>2,3</sup>	$V_{GS} = 10 \text{ V}$		2.3	4	nC					
t <sub>d(on)</sub>	Turn-On Delay Time <sup>2,3</sup>	$I_{D} = 1 \text{ A}, R_{G} = 3.3 \Omega,$		3.9	7	ns					
t <sub>r</sub>	Rise Time <sup>2,3</sup>			12.6	24	ns					
$t_{\rm d(off)}$	Turn-Off Delay Time <sup>2,3</sup>	$V_{GS} = 10 \text{ V}, V_{DD} = 30 \text{ V}$		23.1	44	ns					
tf	Fall Time <sup>2,3</sup>			6.7	13	ns					
C <sub>ISS</sub>	Input Capacitance			800	1160	pF					
Coss	Output Capacitance	$V_{DS} = 15 \text{ V}$ f = 1 MHz , $V_{GS} = 0 \text{ V}$		380	550	pF					
Crss	Reverse Transfer Capacitance	1 – 1 MITIZ, VGS – U V		115	170	pF					
Rg	Total Gate Charge	$V_{DS} = 0 \ V$ , $f = 1 \ MHz$ , $V_{GS} = 0 \ V$		1.7	3.4	Ω					

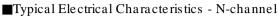
Drain-Sou	Drain-Source Diode Characteristics and Maximum Ratings								
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units			
Is	Continuous Source Current	$V_G = V_D = 0 \ V$ , Force Current			4.5	A			
I <sub>SM</sub>	Pulsed Source Current				9	A			
$V_{SD}$	Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 1 \text{ A}, TJ = 25 ^{\circ}\text{C}$			1	V			

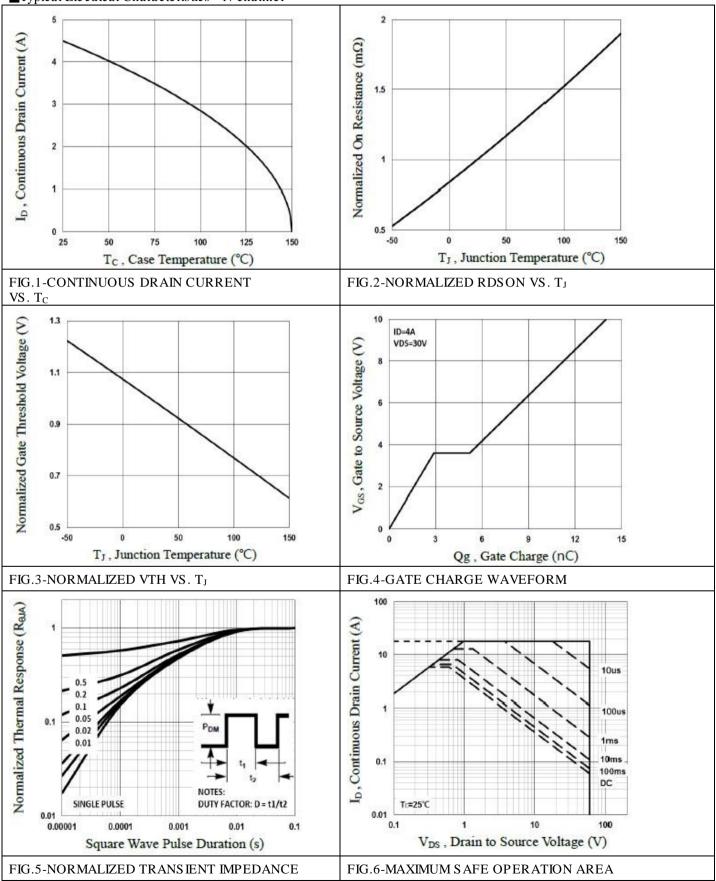
#### Note:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. The data tested by pulsed , pulse width  $\leq 300 \text{us}$  , duty cycle  $\leq 2\%$ .
- 3. Essentially independent of operating temperature.



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P-CH Electrical Characteristics (TJ=25 °C, unless otherwise)

Off Characteristics								
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units		
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = V_{GS}, I_D = 250uA$	-60			V		
$\Delta BV_{DSS}$ / $\Delta TJ$	BV <sub>DSS</sub> Temperature Coefficient	Reference to $25^{\circ}$ C, $I_D = 1 \text{mA}$		-0.05		V/°C		
$I_{GSS}$	Gate-Source Leakage Current	$V_{DS} = 0 \text{ V}$ , $V_{GS} = \pm 20 \text{ V}$			±100	nA		
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{DS} = -60 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $TJ = 25 ^{\circ}\text{C}$ $V_{DS} = -48 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $TJ = 125 ^{\circ}\text{C}$			-1 10	uA		

On Characteristics								
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units		
R <sub>DS(on)</sub> Static Drain-Sour	Statis David Samuel On Basistana	$V_{GS} = -10 \text{ V}, I_D = -6 \text{ A}$		87	105	mΩ		
	Static Drain-Source On-Resistance	$V_{GS} = -4.5 \text{ V}, I_{D} = -3 \text{ A}$		120	145			
$V_{GS(th)}$	Gate Threshold Voltage	V V 250 4	-1.0	-1.6	-2.5	V		
$\Delta V_{GS(th)}$	Temperature Coefficient	$V_{GS} = V_{DS}$ , $I_D = 250 uA$		3		mV/°C		
gfs	Forward Transconductance	$V_{DS} = -10 \text{ V}, I_{D} = -6 \text{ A}$		5.5		S		

Dynamic	Dynamic and switching Characteristics										
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units					
$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{DS} = -30 \text{ V}, I_{D} = -4 \text{ A},$ $V_{GS} = -10 \text{ V}$		10	15	nC					
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>			1.6	3.2	nC					
$Q_{gd} \\$	Gate-Drain Charge <sup>2,3</sup>			3	6	nC					
$t_{d(on)}$	Turn-On Delay Time <sup>2,3</sup>	$I_D = 1 \text{ A}$ , $R_G = 6 \Omega$ ,		8	16	ns					
$t_{\rm r}$	Rise Time <sup>2,3</sup>			15.4	30	ns					
$t_{d(\text{off})}$	Turn-Off Delay Time <sup>2,3</sup>	$V_{GS} = -30 \text{ V}, V_{DD} = -30 \text{ V}$		42.5	80	ns					
tf	Fall Time <sup>2,3</sup>			8.4	16	ns					
Ciss	Input Capacitance			785	1300	pF					
Coss	Output Capacitance	$V_{DS} = -30 \text{ V}$ $f = 1 \text{ MHz} \text{ , } V_{GS} = 0 \text{ V}$		175	300	pF					
C <sub>RSS</sub>	Reverse Transfer Capacitance			112	220	pF					

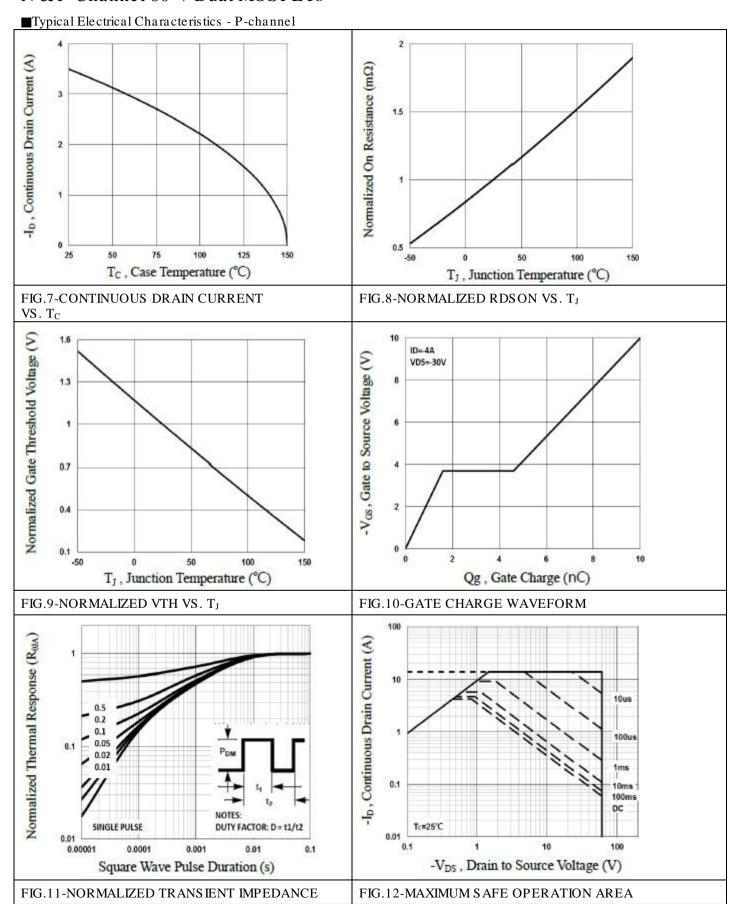
Drain-Sou	Drain-Source Diode Characteristics and Maximum Ratings								
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units			
Is	Continuous Source Current	V <sub>G</sub> = V <sub>D</sub> = 0 V, Force Current			-3.5	A			
I <sub>SM</sub>	Pulsed Source Current				-7	A			
$V_{\mathrm{SD}}$	Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = -1 \text{ A}, TJ = 25 ^{\circ}\text{C}$			-1	V			

#### Note:

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- 3. Essentially independent of operating temperature.



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